

<b>ON Semiconductor</b>				<b>10/15/2019</b>	
<b>Base Part</b>		<b>FDMA530PZ</b>	<b>HF</b>	<b>Pb-free</b>	
<b>Orderable Part</b>		<b>FDMA530PZ</b>	<b>Total weight (mg)</b>	<b>9.879</b>	
<b>Homogenous Material</b>	<b>Weight (mg)</b>	<b>Substance in Mat.</b>	<b>CAS #</b>	<b>% Avg. Weight</b>	
<b>Die</b>	<b>0.569</b>	Silicon (Si)	7440-21-3	100	
<b>Die Attach Epoxy</b>	<b>0.108</b>	Silver (Ag)	7440-22-4	85	
		Phenolic Resin-2	54208-63-8	15	
<b>Lead Frame</b>	<b>4.24</b>	Zinc (Zn)	7440-66-6	0.14150943	
		Iron (Fe)	7439-89-6	2.40566038	
		Copper (Cu)	7440-50-8	97.40566038	
		Phosphorus (P)	7723-14-0	0.04716981	
<b>Mold Compound-Black</b>	<b>4.878</b>	Ortho Cresol Novolac Resin	29690-82-2	10.00410004	
		Carbon Black (C)	1333-86-4	1.00451005	
		Fused Silica (SiO2)	60676-86-0	88.99138991	
<b>Plating</b>	<b>0.049</b>	Palladium (Pd)	7440-05-3	8.16326531	
		Nickel (Ni)	7440-02-0	89.79591837	
		Gold (Au)	7440-57-5	2.04081633	
<b>Wire Bond - Cu</b>	<b>0.035</b>	Copper (Cu)	7440-50-8	100	
<p><b>Materials Disclosure Disclaimer:</b> Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels for dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p><a href="http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF">http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</a></p>					